# **High Voltage Switching Diode**

The BAS21M3T5G device is a spin-off of our popular SOT-23 three-leaded device. It is designed for high voltage switching applications and is housed in the SOT-723 surface mount package. This device is ideal for low-power surface mount applications where board space is at a premium.

#### **Features**

- Reduces Board Space
- This is a Halide-Free Device
- This is a Pb-Free Device

### **MAXIMUM RATINGS** (EACH DIODE)

Rating	Symbol	Value	Unit
Reverse Voltage	V <sub>R</sub>	250	Vdc
Forward Current	ΙF	200	mAdc
Peak Forward Surge Current	I <sub>FM(surge)</sub>	625	mAdc

#### THERMAL CHARACTERISTICS

Characteristic	Symbol	Max	Unit
Total Device Dissipation FR-5 Board (Note 1) T <sub>A</sub> = 25°C Derate above 25°C	P <sub>D</sub>	265 2.1	mW mW/°C
Thermal Resistance, Junction-to-Ambient	$R_{ heta JA}$	470	°C/W
Total Device Dissipation Alumina Substrate, (Note 2) T <sub>A</sub> = 25°C Derate above 25°C	P <sub>D</sub>	640 5.1	mW mW/°C
Thermal Resistance, Junction-to-Ambient	$R_{\theta JA}$	195	°C/W
Junction and Storage Temperature	T <sub>J</sub> , T <sub>stg</sub>	-55 to +150	°C

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

- 1. FR-5 =  $1.0 \times 0.75 \times 0.062$  in.
- 2. Alumina = 0.4  $\times$  0.3  $\times$  0.024 in. 99.5% alumina.



# ON Semiconductor®

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# 250 V HIGH VOLTAGE SWITCHING DIODE



## MARKING DIAGRAM



SOT-723 CASE 631AA STYLE 2



AM = Specific Device Code M = Date Code

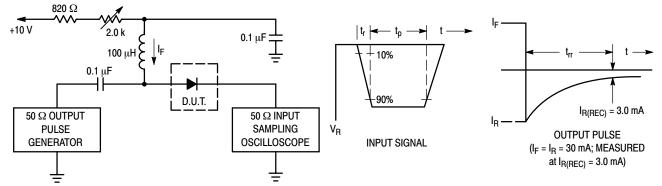
### **ORDERING INFORMATION**

Device	Package	Shipping <sup>†</sup>
BAS21M3T5G	SOT-723 (Pb-Free)	8000/Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

# **ELECTRICAL CHARACTERISTICS** (T<sub>A</sub> = 25°C unless otherwise noted)

Characteristic	Symbol	Min	Max	Unit
Reverse Voltage Leakage Current $(V_R = 200 \text{ Vdc})$ $(V_R = 200 \text{ Vdc}, T_J = 150^{\circ}\text{C})$	I <sub>R</sub>	- -	0.1 100	μAdc
Reverse Breakdown Voltage (I <sub>BR</sub> = 100 μAdc)	V <sub>(BR)</sub>	250	=	Vdc
Forward Voltage (I <sub>F</sub> = 100 mAdc) (I <sub>F</sub> = 200 mAdc)	V <sub>F</sub>		1.0 1.25	Vdc
Diode Capacitance (V <sub>R</sub> = 0, f = 1.0 MHz)	C <sub>D</sub>	-	5.0	pF
Reverse Recovery Time ( $I_F = I_R = 30 \text{ mAdc}$ , $I_{R(REC)} = 3.0 \text{ mAdc}$ , $R_L = 100$ )	t <sub>rr</sub>	-	50	ns

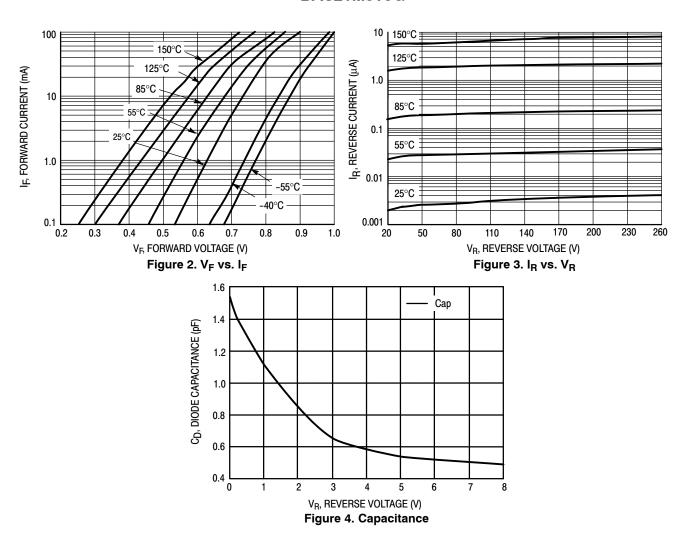


Notes: 1. A 2.0 k $\Omega$  variable resistor adjusted for a Forward Current (IF) of 30 mA.

2. Input pulse is adjusted so  $I_{R(peak)}$  is equal to 30 mA.

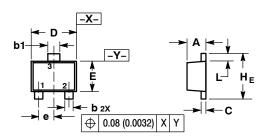
3. t<sub>p</sub> » t<sub>rr</sub>

Figure 1. Recovery Time Equivalent Test Circuit



#### PACKAGE DIMENSIONS

SOT-723 CASE 631AA-01 ISSUE C



STYLE 2: PIN 1. ANODE 2. N/C

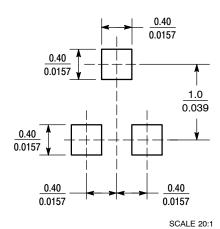
#### NOTES:

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- Y14.5M, 1982.
  2. CONTROLLING DIMENSION: MILLIMETERS.
- MAXIMUM LEAD THICKNESS INCLUDES LEAD
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   THICKNESS OF BASE MATERIAL
- THICKNESS OF BASE MATERIAL.

  4. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS.

	MILLIMETERS			INCHES			
DIM	MIN	NOM	MAX	MIN	NOM	MAX	
Α	0.45	0.50	0.55	0.018	0.020	0.022	
b	0.15	0.21	0.27	0.0059	0.0083	0.0106	
b1	0.25	0.31	0.37	0.010	0.012	0.015	
С	0.07	0.12	0.17	0.0028	0.0047	0.0067	
D	1.15	1.20	1.25	0.045	0.047	0.049	
Е	0.75	0.80	0.85	0.03	0.032	0.034	
a	0.40 BSC			0.016 BSC			
ΗE	1.15	1.20	1.25	0.045	0.047	0.049	
٦	0.15	0.20	0.25	0.0059	0.0079	0.0098	

### **SOLDERING FOOTPRINT\***



\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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